

RBN40H65T1FPQ-A0

650V - 40A - IGBT Power Switching

R07DS1379EJ0121 Rev.1.21 Oct.14.2021

Features

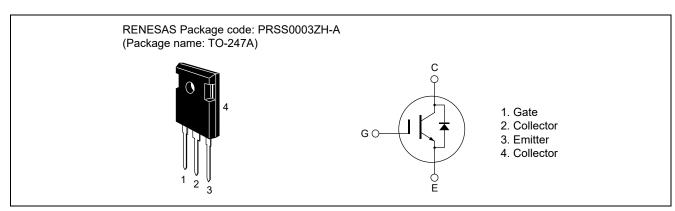
- Trench gate and thin wafer technology (G8H series)
- Built in fast recovery diode in one package
- Low collector to emitter saturation voltage
 V_{CE(sat)} = 1.5 V typ. (at I_C = 40 A, V_{GE} = 15 V, Ta = 25°C)
- · Quality grade: Standard

- · High speed switching
- · Non-specification for short circuit
- Applications: UPS, Welding, photovoltaic inverters, Power converter system

Key Performance

Туре	V _{CES}	lc	V _{CE(sat)} , T _C =25°C	l _F	Tj
RBN40H65T1FPQ-A0	650 V	40 A	1.5 V	30 A	175 °C

Outline



Absolute Maximum Ratings

 $(Tc = 25^{\circ}C)$

Ito	em	Symbol	Ratings	Unit
Collector to emitter volta	ge	V _{CES}	650	V
Gate to emitter voltage		Vges	±30	V
Collector current	Tc = 25 °C	Ic	80	Α
	Tc = 100 °C	Ic	40	Α
Collector peak current		IC(peak) Notes1	160	Α
Diode forward current	Tc = 25 °C	lF	60	Α
	Tc = 100 °C	lf	30	Α
Diode forward peak curre	ent	IF(peak) Notes1	160	Α
Collector power dissipati	on	Pc Notes 2	185	W
Junction temperature		T _j Notes2	175	°C
Storage temperature		T _{stg}	-55 to +150	°C

Note: Continuous heavy condition (e.g. high temperature/voltage/current or high variation of temperature) may affect a reliability even if it is within the absolute maximum ratings. Please consider derating condition for appropriate reliability in reference Renesas Semiconductor Reliability Handbook (Recommendation for Handling and Usage of Semiconductor Devices) and individual reliability data.

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Please use this device in the thermal conditions which the junction temperature does not exceed 175 °C. Renesas IGBT Application Note is disclosed about reliability test and application condition up to 175 °C.

Thermal Resistance Characteristics

 $(Tc = 25^{\circ}C)$

Item	Symbol	Max. Value Notes3	Unit	
Junction to case thermal resistance (IGBT)	R _{th(j-c)}	0.81	°C/W	
Junction to case thermal resistance (Diode)	R _{th(j-c)}	0.97	°C/W	

Notes: 3. Designed target value on Renesas measurement condition. (Not tested)

Electrical Characteristics

 $(Tc = 25^{\circ}C)$

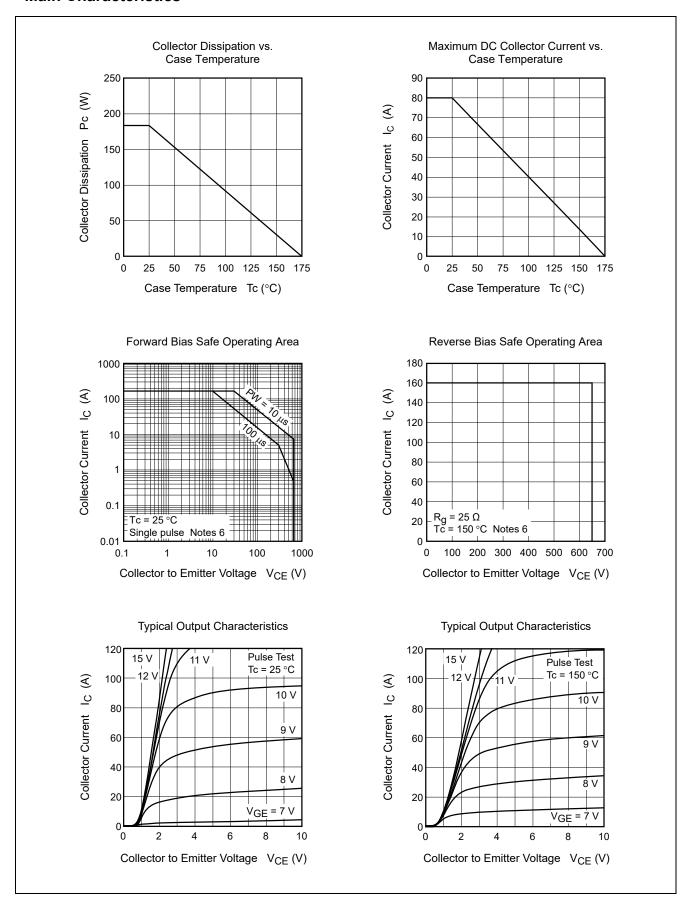
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Collector to emitter leakage current	I _{CES}	_	_	200	μА	V _{CE} = 650 V, V _{GE} = 0 V
Gate to emitter leakage current	Iges	_	_	±1	μА	V _{GE} = ±30 V, V _{CE} = 0 V
Gate to emitter threshold voltage	V _{GE(th)}	4.1	_	5.9	V	$V_{CE} = 10 \text{ V}, I_{C} = 0.8 \text{ mA}$
Collector to emitter saturation voltage	VcE(sat)	_	1.5	2.0	V	Ic = 40 A, V _{GE} = 15 V Notes4
Input capacitance	Cies	_	775	_	pF	V _{CE} = 25 V
Output capacitance	Coes	_	105	_	pF	V _{GE} = 0 V
Reverse transfer capacitance	Cres	l	10	_	pF	f = 1 MHz
Total gate charge	Qg	l	28	_	nC	V _{GE} = 15 V
Gate to emitter charge	Qge	_	7	_	nC	V _{CE} = 400 V
Gate to collector charge	Qgc	1	13	_	nC	Ic = 40 A
Turn-on delay time	t _{d(on)}		22	_	Ns	V _{CC} = 400 V
Rise time	tr		19	_	ns	V _{GE} = +15 V/–5 V
Turn-off delay time	t _{d(off)}	_	96	_	ns	Ic = 40 A
Fall time	tf	_	45	_	ns	$R_g = 16 \Omega$
Turn-on loss energy	Eon		0.62	_	mJ	T _C = 25 °C
Turn-off loss energy	Eoff	_	0.52	_	mJ	Inductive load Notes5
Total switching energy	Etotal	_	1.14	_	mJ	
Turn-on delay time	t _{d(on)}		21	_	Ns	V _{CC} = 400 V
Rise time	tr	_	20	_	ns	V _{GE} = +15 V/–5V
Turn-off delay time	t _{d(off)}	_	120	_	ns	I _C = 40 A
Fall time	t _f	_	60	_	ns	$R_g = 16 \Omega$
Turn-on loss energy	Eon	_	0.98	_	mJ	T _C = 150 °C
Turn-off loss energy	Eoff	_	0.88	_	mJ	Inductive load Notes5
Total switching energy	Etotal	_	1.86	_	mJ	
Diode forward voltage	VF		1.7	2.2	V	I _F = 30 A Notes4
Diode reverse recovery time	t _{rr}	_	55	۷.۷	ne	Ir = 30 A d:r/d; = 300 Δ/us

Diode forward voltage	VF	_	1.7	2.2	V	I _F = 30 A ^{Notes4}
Diode reverse recovery time	t _{rr}	_	55	_	ns	$I_F = 30 \text{ A}, d_{iF}/d_t = 300 \text{ A}/\mu\text{s}$
Diode reverse recovery charge	Qrr	_	0.21		μC	
Diode peak reverse recovery current	I _{rr}	_	7	_	Α	

Notes: 4. Pulse test

5. Switching time test circuit and waveform are shown below.

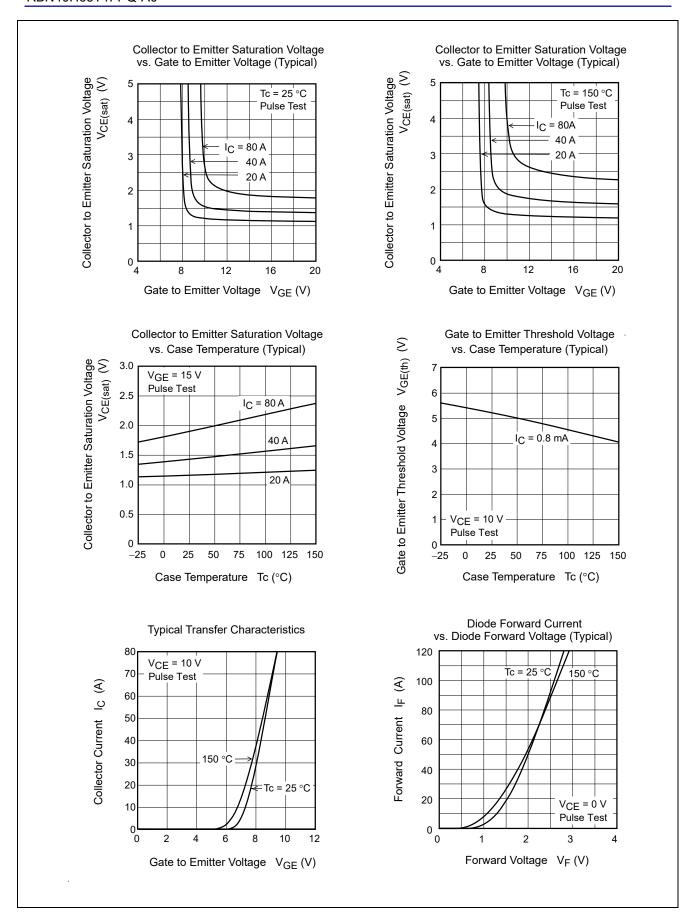
Main Characteristics

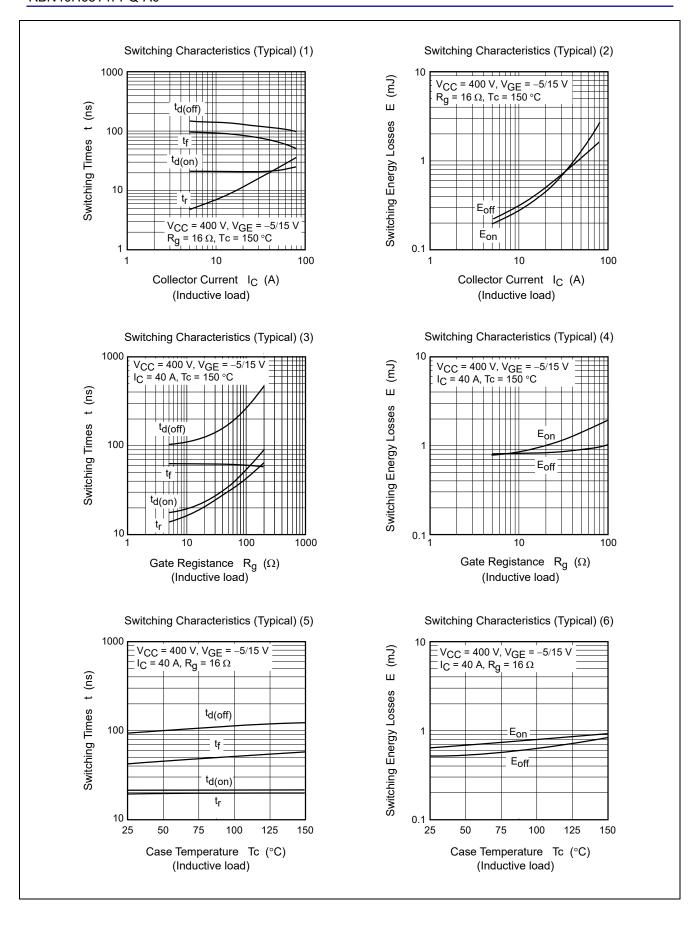


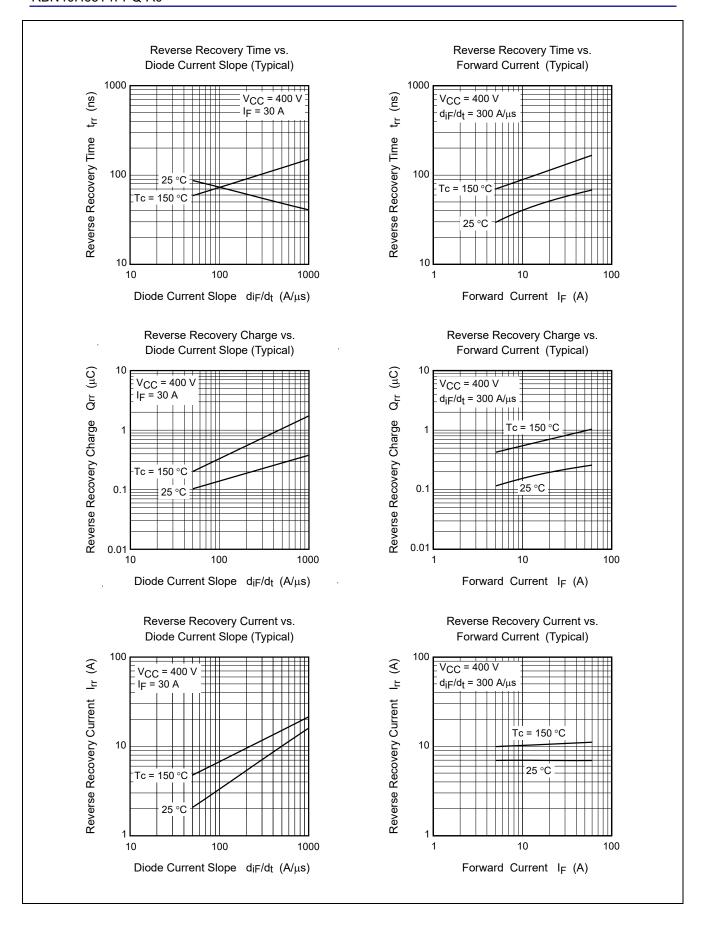
Notes: 6. Designed target value on Renesas measurement condition. (Not tested)

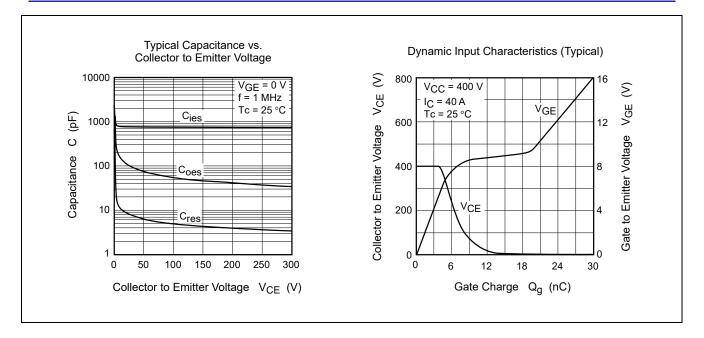
Renesas recommends that operating conditions are designed according to a document "Power MOS FET

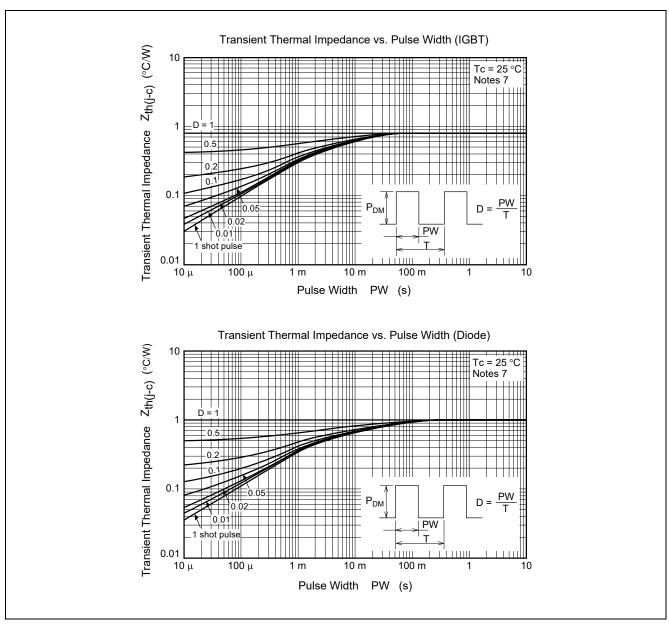
IGBT Attention of Handling Semiconductor Devices".



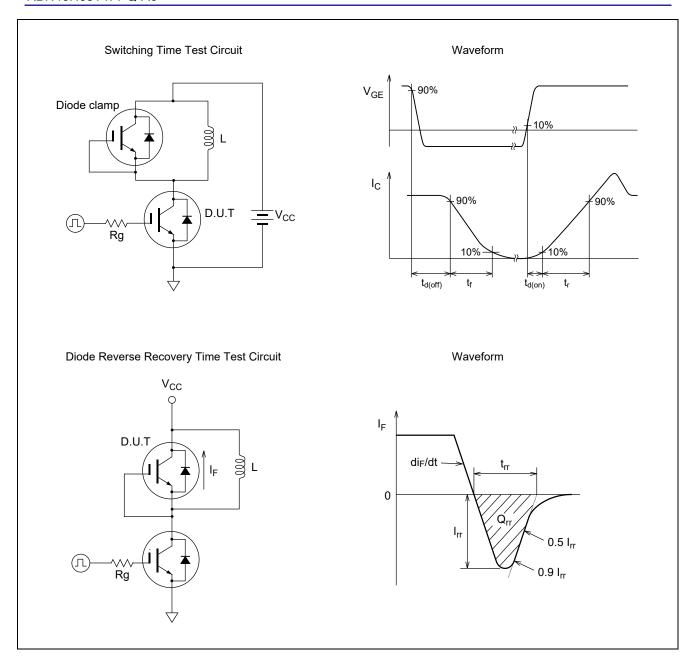




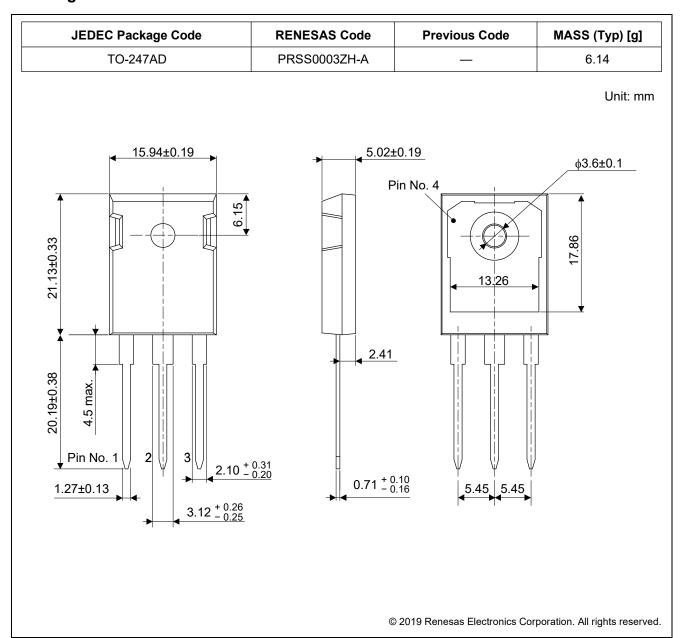




Notes: 7. Designed target value on Renesas measurement condition. (Not tested)



Package Dimensions



Ordering Information

Orderable Part Number	Quantity	Shipping Container		
RBN40H65T1FPQ-A0#CB0	240 pcs	Box (Tube)		

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TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

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